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1.0 GENERAL

THIS SPECIFICATION COVERS .039 INCHES VERTICAL DDR II SOCKETS WITH BLANKED / FORMED CONTACT DESIGNED FOR PRINTED WIRING BOARD TO DUAL IN-LINE MEMORY MODULE INTERCONNECTION. IN ALL APPLICATIONS THE MATED SYSTEM PLATING SHOULD BE TIN TO TIN OR GOLD TO GOLD. THE SPECIFICATION IS COMPOSED OF THE FOLLOWING SECTION.

| <u>PARAGRAPH</u> | <u>TITLE</u> | <u>PAGE</u> |
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| 1.0 | GENERAL | 1 |
| | | 1 |
| 2.0 | APPLICABLE DOCUMENTS | 1 |
| 3.0 | REQUIREMENTS | 2 |
| 3.1 | DESIGN AND CONSTRUCTION | 2 |
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| 3.5 | ELECTRICAL CHARACTERISTICS | 3 |
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| 4.4 | QUALIFICATION TEST SEQUENCE | 6 |
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2.0 APPLICABLE DOCUMENTS

THE FOLLOWING DOCUMENT OF THE ISSUE IN EFFECT ON THE DATE OF THE LATEST REVISION OF THIS SPECIFICATION, SHALL FORM A PART OF THIS SPECIFICATION TO THE EXTENT SPECIFIED HEREIN.

2.1 SPECIFICATIONS

04/14/99

E-3005

FCI ENGINEERING DRAWING 100037402;10057443.

2.2 OTHER STANDARD AND SPECIFICATION

- * UL-94 TESTS FOR FLAMMABILITY OF PLASTIC MATERIALS.
- * EIA 364 ELECTRICAL CONNECTOR/SOCKET TEST PROCEDURES INCLUDE ENVIROMENTAL CLASSIFICATION.
- * EIA-364-1000.01 ENVIRONMENTAL TEST METHODOLOGY FOR ASSESSING THE PERFORMANCE OF ELECTRICAL CONNECTORS AND SOCKETS USED IN BUSINESS OFFICE APPLICATIONS.
- * INTEL "VERTICAL FB DIMM 240 POSITION CONNECTOR SPECIFICATION" VER 1.0.

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2.3 FCI SPECIFICATION

BUS-19-002

SOLDERABILITY TEST.

GS-12-066

DDR PRODUCT SPECIFICATION.

3.0 REQUIREMENTTS

3.1 <u>DESIGN AND CONSTRUCTION</u>

CONNECTORS SHALL BE OF THE DESIGN CONSTRUCTION AND PHYSICAL DIMENSIONS SPECIFIED ON THE APPLICABLE PRODUCT DRAWING.

3.2 MATERIAL

THE MATERIAL FOR EACH PART SHALL BE AS SPECIFIED HEREIN OR EQUIVALENT. THE SUBSTITUTE MATERIAL SHALL MEET THE PERFORMANCE REQIREMENT OF THIS SPECIFICATION.

- 3.2.1 CONTACTS THE CONTACT SHALL BE COPPER ALLOY, POST PLATED.
- 3.2.2 <u>HOUSINGS</u> ALL HOUSING MATERIAL SHALL BE RATED FLAME RETARDANT 94V-0 IN ACCORDANCE WITH UL-94. THE HOUSING SHALL BE GLASS FILLED, NYLON, OR OTHER HIGH PREFORMANCE RESIN.
- 3.2.3 EJECTORS THE MATERIAL OF EJECTOR SHALL BE HIGH PERFORMANCE RESIN.

3.3 FINISH

THE FINISH FOR APPLICABLE COMPONENTS SHALL BE SPECIFIED HEREIN OR EQUIVALENT REFERENCE BUS-02-057

- 3.3.1 CONTACT COATING: GOLD PLATING OVER 50 MICROINCHES MIN. NICKEL UNDERPLATED.
- 3.3.2 SOLDER TAIL COATING: 100~120 MICROINCHES TIN/LEAD OR TIN/COPPER PLATING OVER 50 MICROINCHES MIN. NICKEL UNDERPLATE.
- 3.3.3 CONNECTOR P/N WITH "LF" SUFFIX MEANS LEAD FREE PLATING AND ROHS COMPATIBLE.

3.4 MECHANICAL CHARACTERISTICS

3.4.1 <u>WORKMANSHIP</u> DDR 2 CONNECTORS SHALL BE UNIFORM IN QUALITY AND SHALL BE FREE FROM BURRS, SCRATCH, CRACKS, VOIDS, CHIPS, BLISTERS PINHOLES, AND OTHER DEFECTS THAT WILL ADVERSELY AFFECT THE PERFORMANCE.

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- 3.4.2 <u>CONTACT RETENTION</u> THE INDIVIDUAL CONTACT RETENTION SHALL NOT BE LESS THAN 0.67 LBS (300 gf) WHILE APPLYING A DOWNWARD AXIAL LOAD TO THE SUPPORT MEMBER OF THE CONTACT. (PER EIA 364-29; NO MOVMENT > 0.38 mm)
- 3.4.3 <u>FORKLOCK RETENTION FORCE:</u> THE FORKLOCK RETENTION FORCE SHALL BE 3 LBS MIN PER FORKLOCK. (PER 364-29; NO MOVEMENT > 0.38 mm)
- 3.4.4 <u>DURABILITY</u> AFTER 25 MATING CYCLES WITH MAXIMUM THICKNESS-GAGE AT A RATE OF 5 INCHES / MINUTE. THERE SHALL BE NO DAMAGE TO THE HOUSING OR CONTACTS. THE CONNECTOR SHALL MEET ALL ELECTRICAL AND MECHANICAL CHARACTERISTICS.
- 3.4.5 INSERTION FORCE (CONNECTOR WITH 3 FORKLOCKS TO PCB) INSERT CONNECTOR TO PCB WITH MAX FORKLOCK HOLE (D2.45 +0/-0.05 mm) AND NOMINAL FORKLOCK HOLE (D2.45 +0.05/-0). PER EIA 364-05 AT A RATE OF 0.2 INCHES / MINUTE, THE INSERTION FORCE NO MORE THAN 22.4 LBS.
- 3.4.6 <u>SOLDERABILITY</u> PER EIA 364-52, CLASS 1, CATEGORY 3. THERE SHALL HAVE A SOLDER COVERAGE OF 95% MINIMUM.
- 3.4.7 MATING/UNMATING FORCE THE TOTAL FORCE TO MATE A CONNECTOR AND DDR 2 FBD MODULE SHOULD NOT EXCEED 22 LBS . THE UNMATING FORCE NO LESS THAN 14 gf PER PIN PAIR. TEST PER EIA 364-05 AND EIA 364-13 ACCORDINGLY, WITH SPEED OF 0.2 INCH / MINUTE. THE TEST IS PER EIA AND JEDEC GS-004 MODULE GAUGE.
- 3.4.8 <u>LATCH OPEN FORCE</u> PULL TEST ON LATCH PARALLEL TO PCB SEATING PLAN WITH 1.37 MM FBD MODULE CARD. THE FORCE SHOULD NOT EXCEED 7.3 LBS.
- 3.4.9 <u>MODULE KEYING FEATURE ON LATCH</u> 50 LBS MINIMUM FORCE REQUIRED NOT TO SHEAR OFF KEYING FEATURE IN LATCH.
- 3.4.10 <u>RESEATING</u> MANUAL PLUG/ UNPLUG THE CONNECTOR WITH MODULE BOARD. PERFORM 3 SUCH CYCLES.

3.5 <u>ECECTRICAL CHARACTERISTICS</u>

- 3.5.1 <u>CURRENT RATING</u> THE MAXIMUM TEMPERTURE RISE PER CONDUCTOR SHOULD NO MORE THAN 30 DEGREE C WITH CURRENT OF 0.5 AMPERE / PIN. (PER EIA 364-70).
- 3.5.2 <u>LOW LEVEL CONTACT RESISTANCE</u> THE LOW LEVEL CONTACT RESISTANCE SHALL NOT EXCEED THE VALUE SPECIFIED AS BELOW.

MAXIMUM RESISTANCE (MILLI-OHMS)

TEST PER EIA 364-23 (TERMINATION OF CONNECTOR TO BASE BOARD AND ADD-IN CARD SHALL BE INCLUDED IN MEASUREMENTS).

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- 3.5.3 <u>DIELECTRIC WITHSTANDING VOLTAGE</u> PER EIA 364-20, THERE SHALL NO SHORT CIRCUIT OR INSULATION BREAK DOWN WITH 500 V.
- 3.5.4 <u>INSULATION RESISTANCE</u> PER EIA 364-21, THE INSULATION RESISTANCE SHALL BE 1K MEGOHM MIN WITH VOLTAGE OF 500V.
- 3.5.5 <u>INDUCTANCE</u> PER INTEL "VERTICAL FB DIMM 240 POSITION CONNECTOR SPECIFICATION". MEASURE AT 250 TO 8.0 GHZ. THE SIGNAL LOOP INDUCTANCE L11 SHALL BE 3.7 TO 5.0 NH. MUTUAL INDUCTANCE BETWEEN ADJACENT SIGNALS L12 SHALL BE 2.0 NH MAX.
- 3.5.6 <u>CAPACITANCE</u> PER INTEL "VERTICAL FB DIMM 240 POSITION CONNECTOR SPECIFICATION". MEASURE AT 250 TO 8.0 GHZ. THE C11 (SIGNAL TO GROUND) CAPACITANCE SHOULD BE 1.3 TO 2.0 PF, THE C12 (COUPING CAPACITANCE BETWEEN ADJACENT SIGNALS) SHOULD BE 0.3 PF MAX.

3.6 <u>ENVIRONMENTAL CONDITIONS</u>

- 3.6.1 PHYSICAL SHOCK THERE SHALL BE NO EVIDENCE OF PHYSICAL DAMAGE PER EIA 364-27. WITH TEST CONDITION:
 - (A) 50G, DURATION 11 MS OF TRAPEZOIDAL WAVE.
 - (B) MODULE WEIGHT 90g +/- 10 g (NO HEAT SPREADER) WITH CENTER OF GRAVITY 17~22 mm FROM THE MODULE MATING EDGE.
 - (C) NUMBER OF SHOCKS: 3 SHOCKS IN EACH OF 6 DIRECTIONS APPLIED TO THREE SAMPLE BOARDS.
 - (D) TEST BOARD AS PER INTEL "VERTICAL FB DIMM 240 POSITION CONNECTOR SPECIFICATION" DEFINED.
- 3.6.2 RANDOM VIBRATION THERE SHALL BE NO EVIDENCE OF PHYSICAL DAMAGE AND NO INTERRUPTIONS > 1.0 μ SEC WITH 40g +/- 10g CARD. PER EIA 364-28 WITH TEST CONDITION:
 - (A) FREQUENCY RANGE: 5 HZ ~ 500 HZ .
 - (B) DURATION: 1 HOUR PER AXIS FOR ALL 3 AXIS ON ALL SAMPLES.
 - (C) INPUT ACCELERATION: $5 \sim 20$ HZ (SLOPE): (0.01 g2/HZ)@5 HZ, (0.02g2/HZ)@20 HZ. $20 \sim 500$ HZ (FLAT): (0.02g2/HZ)@20HZ INPUT ACCELERATION IS 3.13 g RMS , RANDOM CONTROL LIMIT TOLERANCE : +/-3 dB.
 - (D) MODULE WEIGHT CAN GO TO 90g +/- 10 g WITH CENTER OF GRAVITY 17~22 mm FROM THE MODULE MATING EDGE WITHOUT PHYSICAL DAMAGE.
- 3.6.3 <u>HIGH TEMPERATURE LIFE</u> TEST PER EIA 364 1000.01. 300 HOURS AT TEMPERATURE 105 DEGREE C.

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- 3.6.4 THERMAL SHOCK: PER EIA 364-32, TEST CONDITION 1. CYCLE THE CONNECTOR –55 TO +85 DEGREE C . DWELL TIME OF 30 MINUTES AT EXTREME TEMPERATURE. TRANSFER TIME 5 MINUTES MAX. NO DAMAGE AFTER 10 CYCLES.
- 3.6.5 CYCLIC TEMPERATURE AND HUMIDITY: PER EIA 364-1000-01, TEST GROUP 2. CYCLE THE CONNECTOR BETWEEN 25 °C \pm 3°C AT 90% RH AND 65 °C \pm 3°C AT 95% RH. RAMP TIMES SHOULD BE 2 HOURS AND DWELL TIMES SHOULD BE 2 HOURS. DWELL TIMES START WHEN THE TEMPERATURE AND HUMIDITY HAVE STABILIZED WITHIN THE SPECIFIED LEVELS. PERFORM 60 SUCH CYCLES. (PROCEDURE PER EIA 364-31)
- 3.6.6 <u>MIXED FLOWING GAS:</u> PER EIA 364 1000.01, CLASS IIA. PERFORM 5 DAYS TO SIMULATE A 3-YEAR FIELD LIFE FOR GOLD FLASH CONTACT PLATING. 7 DAYS(OR ABOVE) TO SIMULATE A 5-YEAR FIELD LIFE FOR 15U" OR ABOVE CONTACT GOLD PLATING.
- 3.6.7 THERMAL DISTURBANCE: CYCLE THE CONNECTOR BETWEEN 15 $^{\circ}$ C \pm 3 $^{\circ}$ C AND 85 $^{\circ}$ C \pm 3 $^{\circ}$ C , AS MEASURED ON THE PART. RAMPS SHOULD BE A MINIMUM OF 1 $^{\circ}$ C PER MINUTE, AND DWELL TIMES SHOULD INSURE THAT THE CONTACTS REACH THE TEMPERATURE EXTREMES(A MINIMUM OF 5 MINUTES) . HUMIDITY IS NOT CONTROLLED. PER EIA 364-1000.01 TEST GROUP 4 . PERFORM 10 SUCH CYCLES.
- 3.6.8 DUST: PER EIA 364-91, THE TEST SPECIMENS SHALL BE UNMATED DURING THE TEST.
- 3.6.9 THERMAL CYCLING: CYCLE THE CONNECTOR BETWEEN 15 $^{\circ}$ C \pm 3 $^{\circ}$ C AND 85 $^{\circ}$ C \pm 3 $^{\circ}$ C , AS MEASURED ON THE PART. RAMPS SHOULD BE A MINIMUM OF 1 $^{\circ}$ C PER MINUTE, AND DWELL TIMES SHOULD INSURE THAT THE CONTACTS REACH THE TEMPERATURE EXTREMES(A MINIMUM OF 5 MINUTES) . HUMIDITY IS NOT CONTROLLED. PER EIA 364-1000.01 TEST GROUP 5 . PERFORM 500 SUCH CYCLES.

4.0 PRODUCT QUALIFICATION PROVISIONS

- 4.1 <u>EQUIPMENT CALIBRATION</u> ALL TEST EQUIPMENT AND INSPECTION FACILITIES USED IN THE PERFORMANCE OF ANY TEST SHALL BE MAINTAINED A CALIBRATION SYSTEM IN ACCORDANCE WITH MIL-C-45662.
- 4.2 <u>INSPECTION CONDITIONS</u> UNLESS OTHERWISE SPECIFIED HEREIN, ALL INSPECTIONS SHALL BE PERFORMED UNDER THE FOLLOWING AMBIENT CONDITION.
 - (a) TEMPERATURE: 25 + / 5 DEGREE C.
 - (b) RELATIVE HUMIDITY: 30 TO 80%
 - (c) BAROMETRIC PRESSURE: LOCAL AMBIENT
- 4.3 SAMPLE QUANITY AND DESCRIPTION:

SAMPLES SHALL BE SELECTED AT RANDOM FROM CURRENT PRODUCTION. THE SAMPLE SIZE SHALL BE ACCORDING TO TEST SEQUENCE NEEDED.

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4.4 QUALIFICATION TEST SEQUENCE:

| | Refer | TEST SEQUENCE | | | | | | |
|--|------------|---------------|------------|-------------|----------------|------------|------------|------------|
| Test Items | to | GROUP 1 | GROUP 2 | GROUP 3 | GROUP 4 | GROUP 5 | GROUP 6 | GROUP 7 |
| Insertion Force (Connector with 3 forklock to PCB) | 3.4.5 | | | | | 1 | | |
| Mating/ Unmating Force | 3.4.7 | | | | | 2 | | |
| Contact Retention | 3.4.2 | | | | | 3 | | |
| Forklock Retention Force | 3.4.3 | | | | | 4 | | |
| Physical Shock | 3.6.1 | | | 6 | | | | |
| Random Vibration | 3.6.2 | | | 4 | | | | |
| Inductance | 3.5.5 | | | | | | | 1 |
| Capacitance | 3.5.6 | | | | | | | 2 |
| Solderability | 3.4.6 | | | | | 5 | | |
| Durability | 3.4.4 | 2 | 2 | 2 | 2 | | 3 | |
| LLCR | 3.5.2 | 1,4,6 | 1,4,7, | 1,3,5, 7 | 1,4,6, 8,10 | | 2,5 | |
| Insulation Resistance | 3.5.4 | | 6 | | | | | |
| Dielectric Withstanding Voltage | 3.5.3 | | | | | | 1,4 | |
| Current Rating | 3.5.1 | | | | | | | 3 |
| High Temperture Life | 3.6.3 | 3 | | | 3 | | | |
| Cycling Temperature & Humitity | 3.6.5 | | 5 | | | | | |
| Thermal Disturbance | 3.6.7 | | | | 7 | | | |
| Thermal Shock | 3.6.4 | | 3 | | | | | |
| Mixed Flowing Gas | 3.6.6 | | | | 5 | | | |
| Reseating | 3.4. 10 | 5 | 8 | | 9 | | | |
| Sample Quantity | | 5 | 5 | 5 | 5 | 5 | 5 | 5 |

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| Test Items | to | GROUP 8 | GROUP 9 | GROUP 10 | GROUP 11 | | |
| Latch Open Force | 3.4.8 | | 1 | 10 | | | |
| Module keying feature strength | 3.4.9 | | 2 | | | | |
| Contact Retention | 3.4.2 | | | | | | |
| Forklock Retention Force | 3.4.3 | | | | | | |
| Physical Shock | 3.6.1 | | | | | | |
| Random Vibration | 3.6.2 | 5 | | | | | |
| Inductance | 3.5.5 | | | | | | |
| Capacitance | 3.5.6 | | | | | | |
| Solderability | 3.4.6 | | | | | | |
| Durability | 3.4.4 | 2 | | 2 | 2 | | |
| LLCR | 3.5.2 | 1,4,6 | | 1,4,6, | 1,4,6, | | |
| Insulation Resistance | 3.5.4 | | | | | | |
| Dielectric Withstanding Voltage | 3.5.3 | | | | | | |
| Current Rating | 3.5.1 | | | | | | |
| High Temperture Life | 3.6.3 | 3 | | 3 | | | |
| Cycling Temperature & Humitity | 3.6.5 | | | | | | |
| Thermal Disturbance | 3.6.7 | | | 5 | 5 | | |
| Thermal Shock | 3.6.4 | | | | | | |
| Mixed Flowing Gas | 3.6.6 | | | | | | |
| Reseating | 3.4. 10 | | | 7 | 7 | | |
| Dust | 3.6.8 | | | | 3 | | |
| Sample Quantity | | 5 | 5 | 5 | 5 | | |

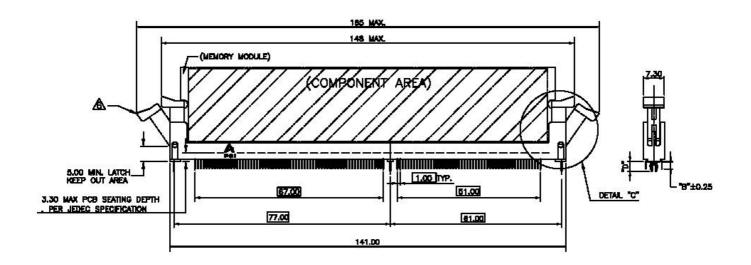
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5 PACKAGING AND SHIPPING

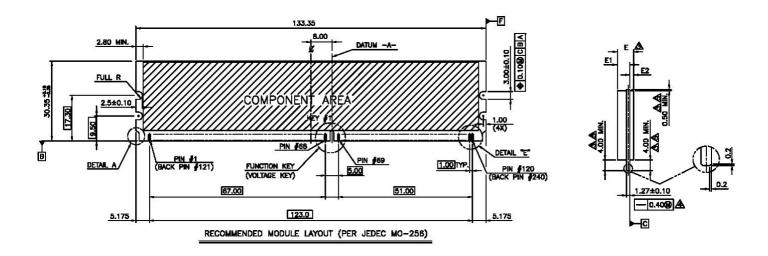
- 5.3 PACKING THE PACKING AND PACKAGING SHALL BE IN ACCORDANCE WITH INDUSTRY STANDARD PRACTICE IN A MANNER TO INSURE CARRIER ACCEPTANCE AND SAFE DELIVERY TO DESTINATION PER FCI PACKAGING SPECIFICATION.
- 5.4 PACKAGING MARKING EACH SHIPPING CONTAINER SHALL BE CLEARLY MARKED WITH THE NAME OF THE CONTENTS, THE AMOUNT OF CONTAINED, THE FCI PART NUMBER, AND THE NAME OF THE RECEIVING PART, AS LISTED IN THE PROCUREMENT.
- 6 <u>THE PROFILE OF DDR 2 FBD CONNECTOR</u>: (PLEASE SEE FCI CUSTOMER DRAWING 10037402 FOR DETAILS)

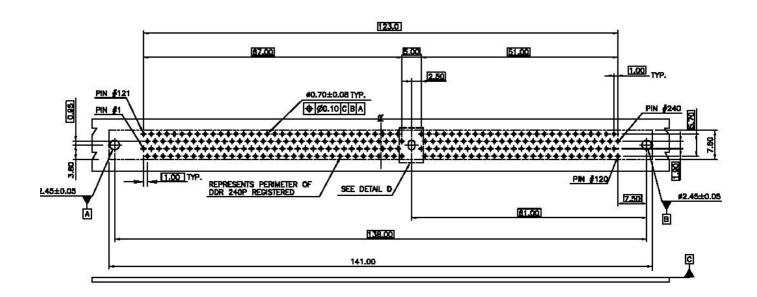


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REVISION RECORD

| REV | PAGE | DESCRIPTION | EC# | DATE |
|-----|----------|---|---------------|-----------|
| Α | All | NEW RELEASE | T04-0323 | 7/15/04 |
| В | 2,3,4,5, | PAGE 2, SEC 3.3.1 CHANGE TO 50 MICR PAGE 3, ADD SEC 3.4.10 PAGE 4, SEC 3.5.4 CHANGE TO 3.5.5 SEC 3.5.5 CHANGE TO 3.5.6 PAGE 5, ADD SEC 3.6.8 PAGE 7, ADD GROUPS 8, 9, 10, 11 | T04-0335 | 7/22/04 |
| С | 7 | PAGE 7, ADD GROUP 12, Modify GROUP 10, Change Test Item 1 st and 2nd (for only this page). | T04-0389 | 10/07/04 |
| D | 3,4,5 | PAGE 3, SEC 3.4.7 CHANGE 35 LBS TO 24 LBS PAGE 3, SEC 3.5.2 CHANGE DELTA R TO BE 10 PAGE 4, SEC 3.5.4 CHANGE TO 1K MEG-OHM PAGE 4, SEC 3.6.2 CHANGE DURATION TO BE 1 HOUR. AND ADDED NO INTERRUPTIONS> 1.0 μ SEC PAGE 5, SEC 3.6.5 CHANGE 90~95%RH, 2 HOURS DWELL AND RAMP; 60 CYCLES | T05-0001 | 01/04/05 |
| Е | 2,3,5,7 | PAGE 2, ADD SEC. 3.3.3 PAGE 3, SEC. 3.4.7, MATING FORCE TO BE 22 LBS. PAGE 5, MODIFY SEC. 3.6.6 PAGE 5, MODIFY SEC. 3.6.7 RAMPS TO BE 1 DEGREE C PER MIN. PAGE 5, ADD SEC. 3.6.9. PAGE 7, REPLACE GROUP 9 BY GROUP 12. | T05-0076 | 04/11/05' |
| F | 1 | Sec 2.1 Added P/N:10057443 | T05-0232 | 10/14/05' |
| G | 4 | PAGE 4, SEC. 3.6.1; CHANGE MODULE CARD WEIGHT FROM 40g to 90g. 3.6.2; TEST DESCRIPTION AND ITEM D. | T06-0072 | 04/10/06' |
| Н | 1,3 | Sec. 2.2 – CHANGE INTEL "" VER "0.51" FROM "0.51"TO "1.0" Sec 3.4.7 – ADD TO THIS SECTION THATTHE TEST IS PER EIA AND JEDEC GS -004 MODULE GAUGE. Sec 3.4.9 – CHANGE 35 LBS TO 50 LBS. | DG06- 0166 | 04/17/06' |

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